

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>CHENG-HUNG CHEN</td> <td>08/01/2013</td> </tr> <tr> <td>JAW-JUNG SHIN</td> <td>08/01/2013</td> </tr> <tr> <td>SHY-JAY LIN</td> <td>08/02/2013</td> </tr> <tr> <td>WEN-CHUAN WANG</td> <td>08/02/2013</td> </tr> <tr> <td>PEI-YI LIU</td> <td>08/01/2013</td> </tr> <tr> <td>BURN JENG LIN</td> <td>08/02/2013</td> </tr> </tbody> </table>		Name	Execution Date	CHENG-HUNG CHEN	08/01/2013	JAW-JUNG SHIN	08/01/2013	SHY-JAY LIN	08/02/2013	WEN-CHUAN WANG	08/02/2013	PEI-YI LIU	08/01/2013	BURN JENG LIN	08/02/2013
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<table border="1"> <tr> <td>Name:</td> <td>TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.</td> </tr> <tr> <td>Street Address:</td> <td>NO. 8, LI-HSIN RD. 6</td> </tr> <tr> <td>Internal Address:</td> <td>SCIENCE BASED INDUSTRIAL PARK</td> </tr> <tr> <td>City:</td> <td>HSIN-CHU</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>300-77</td> </tr> </table>		Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.	Street Address:	NO. 8, LI-HSIN RD. 6	Internal Address:	SCIENCE BASED INDUSTRIAL PARK	City:	HSIN-CHU	State/Country:	TAIWAN	Postal Code:	300-77		
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Application Number:	13954635														
CORRESPONDENCE DATA															
Fax Number:	(214)200-0853														
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<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>															
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ATTORNEY DOCKET NUMBER:	24061.2547														

PATENT

NAME OF SUBMITTER:	DAVID M. O'DELL
Signature:	/David M. O'Dell/
Date:	10/24/2013
Total Attachments: 3 source=24061-2547_Assignment#page1.tif source=24061-2547_Assignment#page2.tif source=24061-2547_Assignment#page3.tif	

Docket No.: 2013-0391/24061.2547
Customer No.: 000042717

ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|-----------------|----|---|
| (1) | Cheng-Hung Chen | of | 9F, No. 3, Liujiia 8th Street, Zhubei City
Hsinchu County 302
Taiwan, R.O.C. |
| (2) | Jaw-Jung Shin | of | 10F, No. 72-11, Lane 531, Section 1
Guangfu Road, East District
Hsinchu City 300, Taiwan, R.O.C |
| (3) | Shy-Jay Lin | of | No. 15, Alley 36, Lane 134
Yuanshan Road, Jhudong Township
Hsinchu County 310, Taiwan, R.O.C. |
| (4) | Wen-Chuan Wang | of | 3F-2, No. 133, Jiangong 1st Road
East District, Hsinchu City 300
Taiwan, R.O.C. |
| (5) | Pei-Yi Liu | of | No. 62, Lane 200, Zhuhe Road
Changhua City, Changhua County 500
Taiwan R.O.C. |
| (6) | Burn Jeng Lin | of | 153 Guang Fu Road, Section 1, Lane 89.
1st Floor, HsinChu City
Taiwan, R.O.C. |

have invented certain improvements in

METHOD FOR ELECTRON-BEAM PROXIMITY CORRECTION WITH IMPROVED CRITICAL DIMENSION ACCURACY

for which we have filed an application for Letters Patent of the United States of America,

 of even date filed herewith; and
 X filed on July 30, 2013, and assigned application number 13/954,635; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and

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interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Cheng-Hung Chen

Residence Address: 9F, No. 3, Liujia 8th Street
Zhubei City, Hsinchu County 302 Taiwan, R.O.C.


Dated: 2013. Aug. 01


Inventor Signature

Inventor Name: Jaw-Jung Shin

Residence Address: 10F, No. 72-11, Lane 531, Section 1, Guangfu Road, East District
Hsinchu City 300, Taiwan, R.O.C

Dated: Aug 01, 2013


Inventor Signature

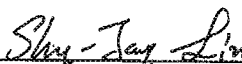
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Inventor Name: Shy-Jay Lin

Residence Address: No. 15, Alley 36, Lane 134, Yuanshan Road
Jhudong Township, Hsinchu County 310, Taiwan, R.O.C.

Dated: 8/2/2013


Inventor Signature

Inventor Name: Wen-Chuan Wang

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Dated: 08/02/2013


Inventor Signature

Inventor Name: Pei-Yi Liu

Residence Address: No. 62, Lane 200, Zhuhe Road
Changhua City, Changhua County 500 Taiwan R.O.C.

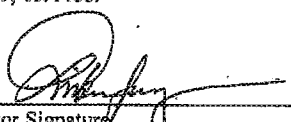
Dated: 2013. Aug. 01


Inventor Signature

Inventor Name: Burn Jeng Lin

Residence Address: 153 Guang Fu Road, Section 1, Lane 89, 1st Floor
HsinChu City Taiwan, R.O.C.

Dated: Aug 2, 2013


Inventor Signature